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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gp304-e-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Diagrams



4.2 Data Address Space

The dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 CPU has a separate 16-bit wide data memory space. The data space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps is shown in Figure 4-3.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the data space. This arrangement gives a data space address range of 64 Kbytes or 32K words. The lower half of the data memory space (that is, when EA<15> = 0) is used for implemented memory addresses, while the upper half (EA<15> = 1) is reserved for the Program Space Visibility area (see Section 4.8.3 "Reading Data from Program Memory Using Program Space Visibility").

dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 devices implement up to 2 Kbytes of data memory. Should an EA point to a location outside of this area, an all-zero word or byte will be returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all data space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC[®] MCU devices and improve data space memory usage efficiency, the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 instruction set supports both word and byte operations. As a consequence of byte accessibility, all effective address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word that contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address. All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the instruction occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the Least Significant Byte. The Most Significant Byte is not modified.

A sign-extend instruction (SE) is provided to allow users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a zero-extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0x0000 to 0x07FF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control, and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'. A complete listing of implemented SFRs, including their addresses, is shown in Table 4-1 through Table 4-22.

Note:	The actual set of peripheral features and						
	interrupts varies by the device. Refer to						
	the corresponding device tables and						
	pinout diagrams for device-specific						
	information.						

4.2.4 NEAR DATA SPACE

The 8 Kbyte area between 0x0000 and 0x1FFF is referred to as the Near Data Space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. Additionally, the whole data space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an address pointer.

Symbol	Parameter	Value		
Vpor	POR threshold	1.8V nominal		
TPOR	POR extension time	30 μs maximum		
VBOR	BOR threshold	2.5V nominal		
Твок	BOR extension time	100 μs maximum		
TPWRT	Programmable power-up time delay	0-128 ms nominal		
TFSCM	Fail-Safe Clock Monitor Delay	900 μs maximum		

TABLE 6-2: OSCILLATOR PARAMETERS

Note: When the device exits the Reset condition (begins normal operation), the device operating parameters (voltage, frequency, temperature, etc.) must be within their operating ranges, otherwise the device may not function correctly. The user application must ensure that the delay between the time power is first applied, and the time SYSRST becomes inactive, is long enough to get operating parameters within all specification.

6.4 Power-on Reset (POR)

A Power-on Reset (POR) circuit ensures the device is reset from power-on. The POR circuit is active until VDD crosses the VPOR threshold and the delay TPOR has elapsed. The delay TPOR ensures the internal device bias circuits become stable.

The device supply voltage characteristics must meet the specified starting voltage and rise rate requirements to generate the POR. Refer to Section 22.0 "Electrical Characteristics" for details.

The POR status (POR) bit in the Reset Control (RCON<0>) register is set to indicate the Power-on Reset.

6.4.1 Brown-out Reset (BOR) and Power-up timer (PWRT)

The on-chip regulator has a Brown-out Reset (BOR) circuit that resets the device when the VDD is too low (VDD < VBOR) for proper device operation. The BOR circuit keeps the device in Reset until VDD crosses VBOR threshold and the delay TBOR has elapsed. The delay TBOR ensures the voltage regulator output becomes stable.

The BOR status bit in the Reset Control register (RCON<1>) is set to indicate the Brown-out Reset.

The device will not run at full speed after a BOR as the VDD should rise to acceptable levels for full-speed operation. The PWRT provides power-up time delay (TPWRT) to ensure that the system power supplies have stabilized at the appropriate levels for full-speed operation before the SYSRST is released.

The power-up timer delay (TPWRT) is programmed by the Power-on Reset Timer Value Select bits (FPWRT<2:0>) in the POR Configuration register (FPOR<2:0>), which provide eight settings (from 0 ms to 128 ms). Refer to **Section 19.0 "Special Features"** for further details.

Figure 6-3 shows the typical brown-out scenarios. The reset delay (TBOR + TPWRT) is initiated each time VDD rises above the VBOR trip point



6.5 External Reset (EXTR)

The external Reset is generated by driving the MCLR pin low. The MCLR pin is a Schmitt trigger input with an additional glitch filter. Reset pulses that are longer than the minimum pulse-width will generate a Reset. Refer to **Section 22.0 "Electrical Characteristics"** for minimum pulse-width specifications. The External Reset (MCLR) Pin (EXTR) bit in the Reset Control (RCON) register is set to indicate the MCLR Reset.

6.5.1 EXTERNAL SUPERVISORY CIRCUIT

Many systems have external supervisory circuits that generate reset signals to Reset multiple devices in the system. This external Reset signal can be directly connected to the MCLR pin to Reset the device when the rest of system is Reset.

6.5.2 INTERNAL SUPERVISORY CIRCUIT

When using the internal power supervisory circuit to Reset the device, the external reset pin (MCLR) should be tied directly or resistively to VDD. In this case, the MCLR pin will not be used to generate a Reset. The external reset pin (MCLR) does not have an internal pull-up and must not be left unconnected.

6.6 Software RESET Instruction (SWR)

Whenever the RESET instruction is executed, the device will assert SYSRST, placing the device in a special Reset state. This Reset state will not re-initialize the clock. The clock source in effect prior to the RESET instruction will remain. SYSRST is released at the next instruction cycle, and the reset vector fetch will commence.

The Software Reset (Instruction) Flag bit (SWR) in the Reset Control register (RCON<6>) is set to indicate the software Reset.

6.7 Watchdog Time-out Reset (WDTO)

Whenever a Watchdog <u>time-out</u> occurs, the device will asynchronously assert <u>SYSRST</u>. The clock source will remain unchanged. A WDT time-out during Sleep or Idle mode will wake-up the processor, but will not reset the processor.

The Watchdog Timer Time-out Flag (WDTO) bit in the Reset Control register (RCON<4>) is set to indicate the Watchdog Reset. Refer to **Section 19.4 "Watchdog Timer (WDT)**" for more information on Watchdog Reset.

6.8 Trap Conflict Reset

If a lower-priority hard trap occurs while a higher-priority trap is being processed, a hard trap conflict Reset occurs. The hard traps include exceptions of priority level 13 through level 15, inclusive. The address error (level 13) and oscillator error (level 14) traps fall into this category.

The Trap Reset Flag bit (TRAPR) in the Reset Control register (RCON<15>) is set to indicate the Trap Conflict Reset. Refer to **Section 7.0 "Interrupt Controller**" for more information on trap conflict Resets.

REGISTER 7-8: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0 (CONTINUED)

bit 1	IC1IE: Input Capture Channel 1 Interrupt Enable bit
-------	---

- 1 = Interrupt request enabled
- 0 = Interrupt request not enabled
- INTOIE: External Interrupt 0 Enable bit
- 1 = Interrupt request enabled

bit 0

0 = Interrupt request not enabled

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	
—	—	—	—	—	—	—	—	
bit 15							bit 8	
U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0	
—	—	—	_	—	—	U1EIE	—	
bit 7 bit 0								
Legend:								
R = Readable	bit	W = Writable	bit	U = Unimplemented bit, read as '0'				
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cleared x = Bit is unknown				
bit 15-2	Unimplemen	ted: Read as '	0'					
bit 1	bit 1 U1EIE: UART1 Error Interrupt Enable bit							
1 = Interrupt request enabled								
0 = Interrupt request not enabled								

REGISTER 7-10: IEC4: INTERRUPT ENABLE CONTROL REGISTER 4

bit 0 Unimplemented: Read as '0'

8.4 Clock Switching Operation

Applications are free to switch among any of the four clock sources (Primary, LP, FRC and LPRC) under software control at any time. To limit the possible side effects of this flexibility, dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 devices have a safeguard lock built into the switch process.

Note: Primary Oscillator mode has three different submodes (XT, HS and EC), which are determined by the POSCMD<1:0> Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch among the different primary submodes without reprogramming the device.

8.4.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the Configuration register must be programmed to '0'. (Refer to **Section 19.1 "Configuration Bits"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('1'), the clock switching function and Fail-Safe Clock Monitor function are disabled. This is the default setting.

The NOSC control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSC bits (OSCCON<14:12>) reflect the clock source selected by the FNOSC Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled. It is held at '0' at all times.

8.4.2 OSCILLATOR SWITCHING SEQUENCE

Performing a clock switch requires this basic sequence:

- 1. If desired, read the COSC bits (OSCCON<14:12>) to determine the current oscillator source.
- 2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
- Write the appropriate value to the NOSC control bits (OSCCON<10:8>) for the new oscillator source.
- 4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
- 5. Set the OSWEN bit to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically as follows:

1. The clock switching hardware compares the COSC status bits with the new value of the NOSC control bits. If they are the same, the clock switch is a redundant operation. In this

case, the OSWEN bit is cleared automatically and the clock switch is aborted.

- If a valid clock switch has been initiated, the status bits, LOCK (OSCCON<5>) and CF (OSCCON<3>) are cleared.
- 3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator must be turned on, the hardware waits until the Oscillator Start-up Timer (OST) expires. If the new source is using the PLL, the hardware waits until a PLL lock is detected (LOCK = 1).
- 4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
- 5. The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSC bit values are transferred to the COSC status bits.
- The old clock source is turned off at this time, with the exception of LPRC (if WDT or FSCM are enabled) or LP (if LPOSCEN remains set).

Note 1: The processor continues to execute code throughout the clock switching sequence. Timing-sensitive code should not be executed during this time.

- 2: Direct clock switches between any primary oscillator mode with PLL and FRC-PLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.
- 3: Refer to Section 7. "Oscillator" (DS70186) in the "dsPIC33F/PIC24H Family Reference Manual" for details.

8.5 Fail-Safe Clock Monitor (FSCM)

The Fail-Safe Clock Monitor (FSCM) allows the device to continue to operate even in the event of an oscillator failure. The FSCM function is enabled by programming. If the FSCM function is enabled, the LPRC internal oscillator runs at all times (except during Sleep mode) and is not subject to control by the Watchdog Timer.

In the event of an oscillator failure, the FSCM generates a clock failure trap event and switches the system clock over to the FRC oscillator. Then the application program can either attempt to restart the oscillator or execute a controlled shutdown. The trap can be treated as a warm Reset by simply loading the Reset address into the oscillator fail trap vector.

If the PLL multiplier is used to scale the system clock, the internal FRC is also multiplied by the same factor on clock failure. Essentially, the device switches to FRC with PLL on a clock failure.

12.0 TIMER2/3 FEATURE

- Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to Section 11. "Timers" (DS70205) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Timer2/3 feature has 32-bit timers that can also be configured as two independent 16-bit timers with selectable operating modes.

As a 32-bit timer, the Timer2/3 feature permits operation in three modes:

- Two Independent 16-bit timers (Timer2 and Timer3) with all 16-bit operating modes (except Asynchronous Counter mode)
- Single 32-bit timer (Timer2/3)
- Single 32-bit synchronous counter (Timer2/3)

The Timer2/3 feature also supports:

- Timer gate operation
- Selectable Prescaler Settings
- Timer operation during Idle and Sleep modes
- Interrupt on a 32-bit Period Register Match
- Time Base for Input Capture and Output Compare Modules (Timer2 and Timer3 only)
- ADC1 Event Trigger (Timer2/3 only)

Individually, all eight of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed above, except for the event trigger. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON and T3CON registers. T2CON registers are shown in generic form in Register 12-1. T3CON registers are shown in Register 12-2. For 32-bit timer/counter operation, Timer2 is the least significant word (lsw), and Timer3 is the most significant word (msw) of the 32-bit timers.

Note:	For 32-bit operation, T3CON control bits
	are ignored. Only T2CON control bit is
	used for setup and control. Timer2 clock
	and gate inputs are used for the 32-bit
	timer modules, but an interrupt is
	generated with the Timer3 interrupt flags.

12.1 32-Bit Operation

To configure the Timer2/3 feature for 32-bit operation:

- 1. Set the corresponding T32 control bit.
- 2. Select the prescaler ratio for Timer2 using the TCKPS<1:0> bits.
- 3. Set the Clock and Gating modes using the corresponding TCS and TGATE bits.
- 4. Load the timer period value. PR3 contains the most significant word of the value, while PR2 contains the least significant word.
- 5. If interrupts are required, set the interrupt enable bit, T3IE. Use the priority bits T3IP<2:0> to set the interrupt priority. While Timer2 controls the timer, the interrupt appears as a Timer3 interrupt.
- 6. Set the corresponding TON bit.

The timer value at any point is stored in the register pair TMR3:TMR2. TMR3 always contains the most significant word of the count, while TMR2 contains the least significant word.

To configure any of the timers for individual 16-bit operation:

- 1. Clear the T32 bit corresponding to that timer.
- 2. Select the timer prescaler ratio using the TCKPS<1:0> bits.
- 3. Set the Clock and Gating modes using the TCS and TGATE bits.
- 4. Load the timer period value into the PRx register.
- 5. If interrupts are required, set the interrupt enable bit, TxIE. Use the priority bits, TxIP<2:0>, to set the interrupt priority.
- 6. Set the TON bit.

REGISTER 15-2: SPIXCON1: SPIX CONTROL REGISTER 1 (CONTINUED)

- bit 4-2 SPRE<2:0>: Secondary Prescale bits (Master mode)⁽³⁾ 111 = Secondary prescale 1:1
 - 110 = Secondary prescale 2:1
 - •
 - •
 - 000 = Secondary prescale 8:1
- bit 1-0 **PPRE<1:0>:** Primary Prescale bits (Master mode)⁽³⁾
 - 11 = Primary prescale 1:1
 - 10 = Primary prescale 4:1
 - 01 = Primary prescale 16:1
 - 00 = Primary prescale 64:1
- **Note 1:** The CKE bit is not used in the Framed SPI modes. Program this bit to '0' for the Framed SPI modes (FRMEN = 1).
 - 2: This bit must be cleared when FRMEN = 1.
 - 3: Do not set both Primary and Secondary prescalers to a value of 1:1.

REGISTER 16-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 5	ACKDT: Acknowledge Data bit (when operating as I ² C master, applicable during master receive) Value that will be transmitted when the software initiates an Acknowledge sequence. 1 = Send NACK during Acknowledge 0 = Send ACK during Acknowledge
bit 4	 ACKEN: Acknowledge Sequence Enable bit (when operating as I²C master, applicable during master receive) 1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit. Hardware clear at end of master Acknowledge sequence 0 = Acknowledge sequence not in progress
bit 3	RCEN: Receive Enable bit (when operating as I ² C master) 1 = Enables Receive mode for I ² C. Hardware clear at end of eighth bit of master receive data byte 0 = Receive sequence not in progress
bit 2	 PEN: Stop Condition Enable bit (when operating as I²C master) 1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence 0 = Stop condition not in progress
bit 1	 RSEN: Repeated Start Condition Enable bit (when operating as I²C master) 1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence 0 = Repeated Start condition not in progress
bit 0	 SEN: Start Condition Enable bit (when operating as I²C master) 1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence 0 = Start condition not in progress

R-0 HSC	R-0 HSC	U-0	U-0	U-0	R/C-0 HS	R-0 HSC	R-0 HSC	
ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	
bit 15							bit 8	
R/C-0 HS	R/C-0 HS	R-0 HSC	R/C-0 HSC	R/C-0 HSC	R-0 HSC	R-0 HSC	R-0 HSC	
IWCOL	I2COV	D_A	Р	S	R_W	RBF	TBF	
bit 7							bit 0	
Legend:		U = Unimpler	nented bit, rea	ad as '0'				
R = Readable	bit	W = Writable	bit	HS = Set in h	ardware	HSC = Hardwa	are set/cleared	
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown	
bit 15	ACKSTAT: Ac (when operati 1 = NACK rec 0 = ACK rece Hardware set	cknowledge Sta ing as I ² C mas ceived from slave ived from slave or clear at end	atus bit ter, applicable ve e l of slave Ack	to master tran	nsmit operation)		
bit 14	TRSTAT: Tran 1 = Master tra 0 = Master tra Hardware set	nsmit Status bit ansmit is in pro ansmit is not in at beginning c	t (when opera gress (8 bits - progress of master trans	ting as I ² C ma ⊦ ACK) smission. Hard	ister, applicable Iware clear at e	to master trans	smit operation) nowledge.	
bit 13-11	Unimplemen	ted: Read as '	0'					
bit 10	BCL: Master	Bus Collision	Detect bit					
	1 = A bus coll 0 = No collisio Hardware set	lision has been on at detection of	detected dur	ing a master o	peration			
hit 9	GCSTAT: Ger	neral Call Stati	is hit					
	1 = General o 0 = General o Hardware set	all address wa all address wa when address	s received s not received matches gen	d eral call addre	ess. Hardware c	lear at Stop det	ection.	
bit 8	ADD10: 10-bi	it Address Stat	us bit					
	1 = 10-bit add 0 = 10-bit add Hardware set	dress was mato dress was not r at match of 2r	ched natched id byte of mat	ched 10-bit ad	dress. Hardwar	e clear at Stop	detection.	
bit 7	IWCOL: Write	e Collision Dete	ect bit					
	1 = An attemp 0 = No collision Hardware set	ot to write the li on at occurrence	2CxTRN regis	ster failed beca	ause the I ² C mo	dule is busy		
bit 6	I2COV: Recei	ive Overflow Fl	laα bit			contraro).		
	 1 = A byte was received while the I2CxRCV register is still holding the previous byte 0 = No overflow Hardware set at attempt to transfer I2CxRSR to I2CxRCV (cleared by software). 							
bit 5	D_A: Data/Address bit (when operating as I ² C slave) 1 = Indicates that the last byte received was data 0 = Indicates that the last byte received was device address Hardware clear at device address match. Hardware set by reception of slave byte							
bit 4	P: Stop bit					-		
	1 = Indicates 0 = Stop bit w Hardware set	that a Stop bit vas not detecte or clear when	has been det d last Start, Repeat	ected last ed Start or Sto	p detected.			

REGISTER 16-2: I2CxSTAT: I2Cx STATUS REGISTER

17.3 UART Control Registers

REGISTER 17-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN ⁽¹⁾		USIDL	IREN ⁽²⁾	RTSMD		UEN	<1:0>
bit 15						-	bit 8
R/W-0 HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSE	L<1:0>	STSEL
bit 7	•						bit 0
Legend:		HC = Hardwa	e Clearable				
R = Readable	e bit	W = Writable I	oit	U = Unimpler	mented bit, read	d as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 15	UARTEN: UA	RTx Enable bit	(1)				
	1 = UARTx is	s enabled; all U	ARTx pins ar	e controlled by	UARTx as defi	ined by UEN<1	:0>
	0 = UARTx is	disabled; all UA	RTx pins are	controlled by po	ort latches; UAR	Tx power consur	mption minimal
bit 14	Unimplemen	ted: Read as ')'				
bit 13	USIDL: Stop	in Idle Mode bit					
	1 = Discontin	ue module ope	ration when o	device enters lo	dle mode		
	0 = Continue	module operat	ion in Idle mo	ode (2)			
bit 12	IREN: IrDA®	Encoder and D	ecoder Enabl	e bit ⁽²⁾			
	$1 = IrDA^{\otimes} en$	coder and deco	der enabled				
hit 11				.:+			
		ie Selection Ior	UXRIS PILLU Vodo	л			
	$0 = \frac{0xRTS}{0xRTS}p$	in in Flow Cont	rol mode				
bit 10	Unimplemen	ted: Read as ')'				
bit 9-8	UEN<1:0>: U	ARTx Enable b	its				
	11 = UxTX.	UxRX and BCL	K pins are en	abled and use	d: UxCTS pin c	ontrolled by por	rt latches
	10 = $UxTX$,	UxRX, UxCTS	and UxRTS p	ins are enable	d and used		
	$01 = \mathbf{U}\mathbf{x}\mathbf{T}\mathbf{X},$	UxRX and UxR	TS pins are e	nabled an <u>d us</u>	ed; UxCTS pin	controlled by p	ort latches
	s XIXU = 00	and UXRX pins a	are enabled a	and used; UxC	IS and UXRIS	BCLK pins con	trolled by
bit 7	WAKE: Wake	-un on Start hit	Detect Durin	a Sleen Mode	Enable bit		
Sit 7	1 = UARTx w	vill continue to s	ample the Ux	RX pin: interru	int generated o	n falling edge: l	bit cleared
	in hardwa	are on following	rising edge		spr generated e	in raining eage, i	
	0 = No wake	-up enabled					
bit 6	LPBACK: UA	RTx Loopback	Mode Select	bit			
	1 = Enable L	oopback mode					
	0 = Loopbac	k mode is disab	led				
bit 5	ABAUD: Auto	p-Baud Enable	bit				
	1 = Enable b	aud rate measu	urement on th	ne next charact	ter – requires re	eception of a Sy	ync field (55h)
	0 = Baud rate	e measurement	disabled or o	e upon comple completed			
	Buduidu						
Note 1: Re	fer to Section 1	7. "UART" (DS	670188) in the	e "dsPIC33F/P	IC24H Family F	Reference Mani	ual" for
info	ormation on ena	bling the UART	- module for r	eceive or trans	mit operation.		

2: This feature is only available for the 16x BRG mode (BRGH = 0).

21.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC[®] DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

21.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC[®] Flash MCUs and dsPIC[®] Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with incircuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

21.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC[®] Flash microcontrollers and dsPIC[®] DSCs with the powerful, yet easyto-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

21.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC[®] and dsPIC[®] Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming[™].

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

22.2 AC Characteristics and Timing Parameters

The information contained in this section defines dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 AC characteristics and timing parameters.

TABLE 22-14: TEMPERATURE AND VOLTAGE SPECIFICATIONS - AC

	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)				
AC CHARACTERISTICS	Operating temperature -40°C ≤TA ≤+85°C for Industrial				
	-40°C ≤TA ≤+125°C for Extended				
	Operating voltage VDD range as described in Table 22-1.				

FIGURE 22-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



TABLE 22-15: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

	Param No.	Symbol	Characteristic	Min	Тур	Мах	Units	Conditions
Γ	DO50	Cosc2	OSC2/SOSC2 pin	_		15	pF	In XT and HS modes when external clock is used to drive OSC1
1	DO56	Сю	All I/O pins and OSC2	—	_	50	pF	EC mode
l	DO58	Св	SCLx, SDAx	—		400	pF	In I ² C™ mode

FIGURE 22-3: I/O TIMING CHARACTERISTICS



		Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended						
Param No.	Symbol	Characteristic ⁽²⁾		Min	Typ ⁽¹⁾	Max	Units	Conditions
DO31	TioR	Port Output Rise Time			10	25	ns	_
DO32	TIOF	Port Output Fall Time		—	10	25	ns	_
DI35	TINP	INTx Pin High or Low Time (input)		25	_		ns	—
DI40	TRBP	CNx High or Low Tim	ne (input)	2	_	_	TCY	_

TABLE 22-20: I/O TIMING REQUIREMENTS

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: These parameters are characterized, but are not tested in manufacturing.

FIGURE 22-6: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



TABLE 22-25: INPUT CAPTURE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾		Min	Мах	Units	Conditions	
IC10	TccL	ICx Input Low Time	No Prescaler	0.5 Tcy + 20		ns	—	
			With Prescaler	10		ns		
IC11	TccH	ICx Input High Time	No Prescaler	0.5 Tcy + 20	_	ns	—	
			With Prescaler	10	_	ns		
IC15	TccP	ICx Input Period		(Tcy + 40)/N		ns	N = prescale value (1, 4, 16)	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 22-7: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



TABLE 22-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended				
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Тур	Мах	Units	Conditions
OC10	TccF	OCx Output Fall Time	—	—	_	ns	See parameter D032
OC11	TccR	OCx Output Rise Time	—	—	_	ns	See parameter D031

Note 1: These parameters are characterized but not tested in manufacturing.











28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimens	MIN	NOM	MAX	
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

Section Name	Update Description
Section 18.0 "Special Features"	Added FICD register information for address 0xF8000E in the Device Configuration Register Map (see Table 18-1).
	Added FICD register content (BKBUG, COE, JTAGEN, and ICS<1:0> to the dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 Configuration Bits Description (see Table 18-2).
	Added a note regarding the placement of low-ESR capacitors, after the second paragraph of Section 18.2 " On-Chip Voltage Regulator " and to Figure 18-1.
	Removed the words "if enabled" from the second sentence in the fifth paragraph of Section 18.3 "BOR: Brown-out Reset" .
Section 21.0 "Electrical Characteristics"	Updated Max MIPS value for -40°C to +125°C temperature range in Operating MIPS vs. Voltage (see Table 21-1).
	Removed Typ value for parameter DC12 (see Table 22-4).
	Updated MIPS conditions for parameters DC24c, DC44c, DC72a, DC72f and DC72g (see Table 21-5, Table 21-6 and Table 21-8).
	Added Note 4 (reference to new table containing digital-only and analog pin information to I/O Pin Input Specifications (see Table 21-9).
	Updated Typ, Min, and Max values for Program Memory parameters D136, D137, and D138 (see Table 21-12).
	Updated Max value for Internal RC Accuracy parameter F21 for -40°C \leq TA \leq +125°C condition and added Note 2 (see Table 21-19).
	Removed all values for Reset, Watchdog Timer, Oscillator Start-up Timer, and Power-up Timer parameter SY20 and updated conditions, which now refers to Section 18.4 "Watchdog Timer (WDT) " and LPRC parameter F21a (see Table 21-21).
	Updated Min and Typ values for parameters AD60, AD61, AD62 and AD63 and removed Note 3 (see Table 21-37).
	Updated Min and Typ values for parameters AD60, AD61, AD62 and AD63 and removed Note 3 (see Table 21-38).

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)